

Endstufen für FT 736

Mitsubishi-1

Auf dieser und der folgenden Seiten finden Sie alle HF-Leistungsmoduln, die Sie über uns beziehen können. Wir führen die Hersteller Mitsubishi (M), Toshiba (S-AV.., S-AU..), Hitachi (PF...), Motorola (CA...., MHW...), NEC (MC-....), Philips (BGY..) Die meisten Gehäuse, vor allem die von Mitsubishi und Toshiba, sehen wie die links abgebildeten aus, obwohl es von diesen Gehäusen mehrere verschiedene Größen gibt.

Auf dieser und der folgenden Seiten finden Sie alle HF-Leistungsmoduln, die Sie über uns beziehen können. Wir führen die Hersteller Mitsubishi (M), Toshiba (S-AV.., S-AU..), Hitachi (PF...), Motorola (CA...., MHW...), NEC (MC-....), Philips (BGY..) Die meisten Gehäuse, vor allem die von Mitsubishi und Toshiba, sehen wie die links abgebildeten aus, obwohl es von diesen Gehäusen mehrere verschiedene

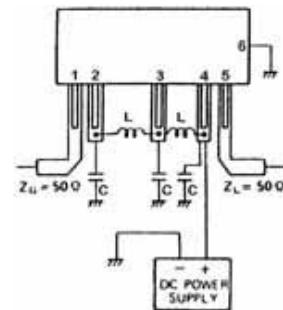
Größen gibt. Die hier angegebene Angaben dienen alle nur zur Orientierung! Ohne Gewähr!

Bei den Mitsubishi-Typen mit dem Zusatz "R" ist die Reihenfolge der Pin's um 180 gedreht, d.h. der HF-Eingang liegt auf der rechten Seite an Pin 4 bzw. 5.

Sonderbeschaffung nur gegen Vorabrechnung lieferbarModule Lieferzeit ca.8 Tage. Zur Zeit ca.40 Typen von Mitsubishi ab Lager lieferbar.

Der Inhalt dieser Webseiten ist urheberrechtlich geschützt. Alle Rechte sind vorbehalten. Kein Teil dieser Webseiten darf ohne unsere ausdrückliche, schriftliche Genehmigung vervielfältigt werden.

Alle angegebenen Daten dienen der Orientierung und sind nicht als zugesicherte Eigenschaften anzusehen; beachten Sie bitte die Datenblätter der Hersteller!



M 57713

Frequenzbereich:144-148 MHzMax. BW: VCC: 12,5 VHF-out Min : 17WattHF in mW: 200Mode: SSBGehäuse: H3B (Siehe Abbildung)

inkl. MwSt **145,95 €**

122,65 €

1

Jetzt kaufen

M 57727

Frequenzbereich:144-148 MHzMax. BW: 140-150VCC: 12,5 VHF-out Min Ohm: 37HF in mW: 300Mode: SSBGehäuse: H3B (Siehe Abbildung)

inkl. MwSt **145,95 €**

122,65 €

1

Jetzt kaufen

http://www.amidon.de/contents/de/d144_01.html

M 57745

M57745
Frequenzbereich:430 - 450 MHzMax. BW: 425 - 450 MHzVCC: 12,5 VHF-out 30WattHF in mW: 300Mode: SSBGehäuse: H3C

inkl. MwSt **169,95 €**

142,82 €

1

Jetzt kaufen

M 57716

M 57716-ab Lager, equivalent SCxx16 (ICOM)

Frequenzbereich:430-450 MHzMax. BW: VCC: 12,5 VHF-out Min Ohm: 17HF in mW: 200Mode: SSBGehäuse: H3C (Siehe Abbildung)NUR PER VORKASSE !!
Datenblatt wird mitgeliefert!!

inkl. MwSt **99,50 €**

83,61 €

1

Jetzt kaufen

M 57762

Frequenzbereich:1240-1300 MHzMax. BW: 1240-1300 MHzVCC: 12,5 VHF-out Min Ohm:18HF in mW: 1000Mode: SSBGehäuse: H3B

inkl. MwSt **189,00 €**

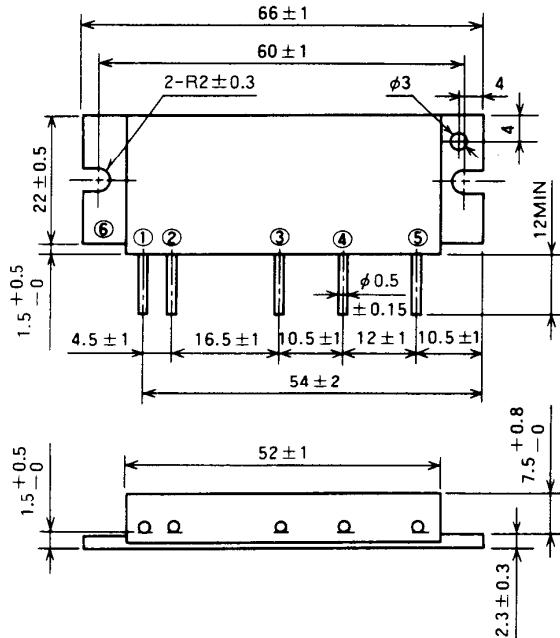
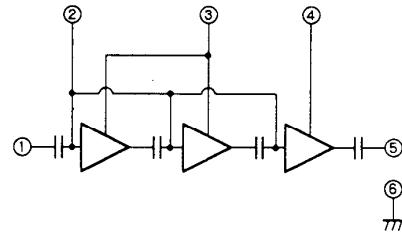
158,82 €

1

Jetzt kaufen

OUTLINE DRAWING

Dimensions in mm

**H3****BLOCK DIAGRAM**

PIN :

- ① Pin : RF INPUT
- ② VBB : BASE BIAS SUPPLY
- ③ VCC1 : 1st. DC SUPPLY
- ④ VCC2 : 2nd. DC SUPPLY
- ⑤ Po : RF OUTPUT
- ⑥ GND : FIN

ABSOLUTE MAXIMUM RATINGS ($T_c = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Ratings	Unit
Vcc	Supply voltage		17	V
VBB	Base bias		10	V
Icc	Total current		6	A
Pin(max)	Input power	$Z_G = Z_L = 50 \Omega$	0.3	W
Po(max)	Output power	$Z_G = Z_L = 50 \Omega$	28	W
Tc(OP)	Operation case temperature		- 30 to 110	°C
Tstg	Storage temperature		- 40 to 110	°C

Note. Above parameters are guaranteed independently.

ELECTRICAL CHARACTERISTICS ($T_c = 25^\circ\text{C}$ unless otherwise noted)

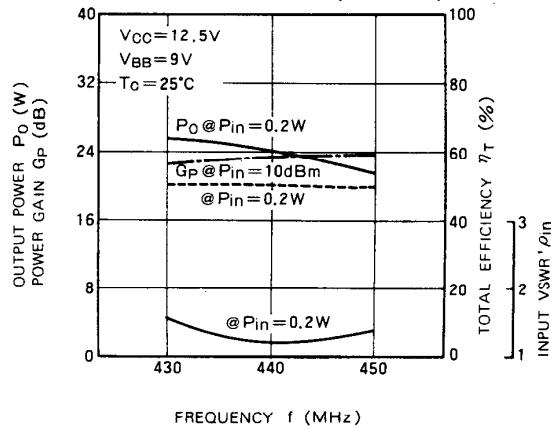
Symbol	Parameter	Test conditions	Limits		Unit
			Min	Max	
f	Frequency range		430	450	MHz
Po	Output power	$P_{in} = 0.2\text{W}$ $V_{cc} = 12.5\text{V}$ $V_{bb} = 9\text{V}$	17		W
η_T	Total efficiency	$Z_G = Z_L = 50 \Omega$	35		%
2fo	2nd. harmonic			- 30	dBc
ρ_{in}	Input VSWR			2.5	-
-	Load VSWR tolerance	$V_{cc} = 15.2\text{V}$, $V_{bb} = 9\text{V}$ $P_{in} = 14\text{W}$ (P_{in} : controlled) Load VSWR=20:1 (All phase), 2sec. $Z_G = 50 \Omega$	No degradation or destroy		-

Note. Above parameters, ratings, limits and conditions are subject to change.

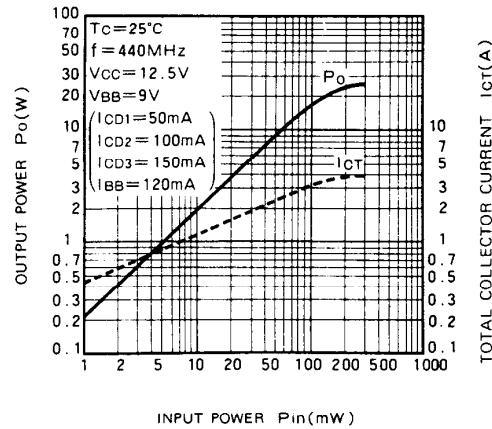
NOV. '97

TYPICAL PERFORMANCE DATA

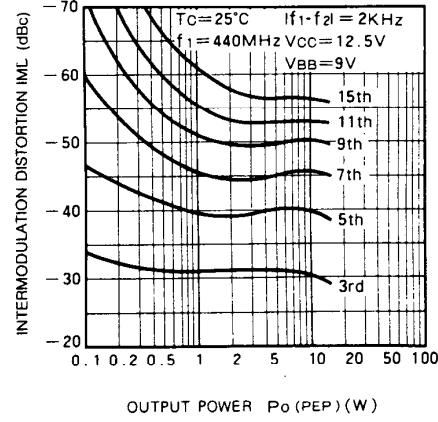
OUTPUT POWER, POWER GAIN, TOTAL EFFICIENCY, INPUT VSWR VS. FREQUENCY CHARACTERISTICS (M57716)



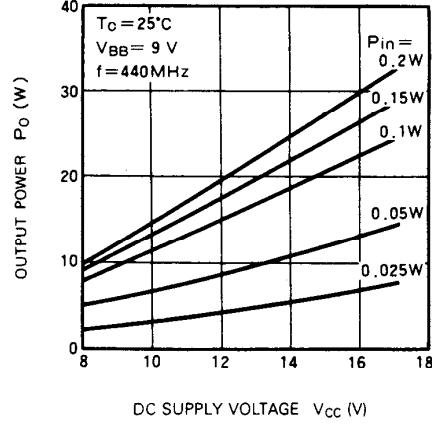
OUTPUT POWER, TOTAL COLLECTOR CURRENT VS. INPUT POWER

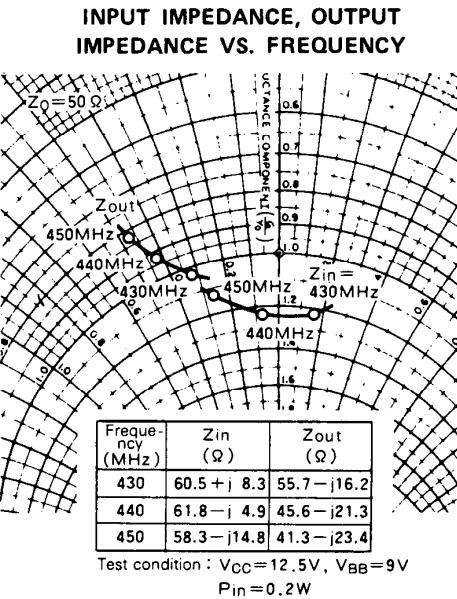


INTERMODULATION DISTORTION VS. OUTPUT POWER



OUTPUT POWER VS. DC SUPPLY VOLTAGE





DESIGN CONSIDERATION OF HEAT RADIATION.

Please refer to following consideration when designing heat sink.

1. Junction temperature of incorporated transistors at standard operation.

(1) Thermal resistance between junction and package of incorporated transistors.

a) First stage transistor

$$R_{th(j-c)1} = 15^\circ\text{C/W (Typ.)}$$

b) Second stage transistor

$$R_{th(j-c)2} = 6^\circ\text{C/W (Typ.)}$$

c) Final stage transistor

$$R_{th(j-c)3} = 2^\circ\text{C/W (Typ.)}$$

(2) Junction temperature of incorporated transistors at standard operation.

- Conditions for standard operation.

$P_0 = 14W$, $V_{CC} = 12.5V$, $P_{in} = 80mW$, $\eta_T = 35\%$ (minimum rating), $P_{O1}^{(Note 1)} = 1W$, $P_{O2}^{(2)} = 4.5W$, $I_T = 3.2A$ ($I_{T1}^{(3)} = 0.15A$, $I_{T2}^{(4)} = 0.55A$, $I_{T3}^{(5)} = 2.5A$)

Note 1: Output power of the first stage transistor

Note 2: Output power of the second stage transistor

Note 3: Circuit current of the first stage transistor

Note 4: Circuit current of the second stage transistor

Note 5: Circuit current of the final stage transistor

- Junction temperature of the first stage transistor

$$\begin{aligned} T_{j1} &= (V_{CC} \times I_{T1} - P_{O1} + P_{in}) \times R_{th(j-c)1} + T_c^{(6)} \\ &= (12.5 \times 0.15 - 1 + 0.08) \times 15 + T_c \\ &= 14.4 + T_c (\text{ }^\circ\text{C}) \end{aligned}$$

Note 6: Package temperature of device

- Junction temperature of the second stage transistor

$$\begin{aligned} T_{j2} &= (V_{CC} \times I_{T2} - P_{O2} + P_{O1}) \times R_{th(j-c)2} + T_c \\ &= (12.5 \times 0.55 - 4.5 + 1) \times 6 + T_c \\ &= 20.3 + T_c (\text{ }^\circ\text{C}) \end{aligned}$$

- Junction temperature of the final stage transistor

$$\begin{aligned} T_{j3} &= (V_{CC} \times I_{T3} - P_0 + P_{O2}) \times R_{th(j-c)3} + T_c \\ &= (12.5 \times 2.5 - 14 + 4.5) \times 2 + T_c \\ &= 43.5 + T_c (\text{ }^\circ\text{C}) \end{aligned}$$

2. Heat sink design

In thermal design of heat sink, try to keep the package temperature at the upper limit of the operating ambient temperature (normally $T_a = 60^\circ\text{C}$) and at the output power of 14W below 90°C .

The thermal resistance $R_{th(c-a)}^{(7)}$ of the heat sink to realize this:

$$\text{Note 7: } R_{th(c-a)} = \frac{T_c - T_a}{(P_0/\eta_T) - P_0 + P_{in}} = \frac{90 - 60}{(14/0.35) - 14 + 0.08} = 1.15 (\text{ }^\circ\text{C/W})$$

Note 7: Inclusive of the contact thermal resistance between device and heat sink.

Mounting the heat sink of the above thermal resistance on the device,

$$T_{j1} = 104.4^\circ\text{C}, T_{j2} = 110.3^\circ\text{C}, T_{j3} = 133.5^\circ\text{C} \text{ at } T_a = 60^\circ\text{C}, T_c = 90^\circ\text{C}.$$

In the annual average of ambient temperature is 30°C ,

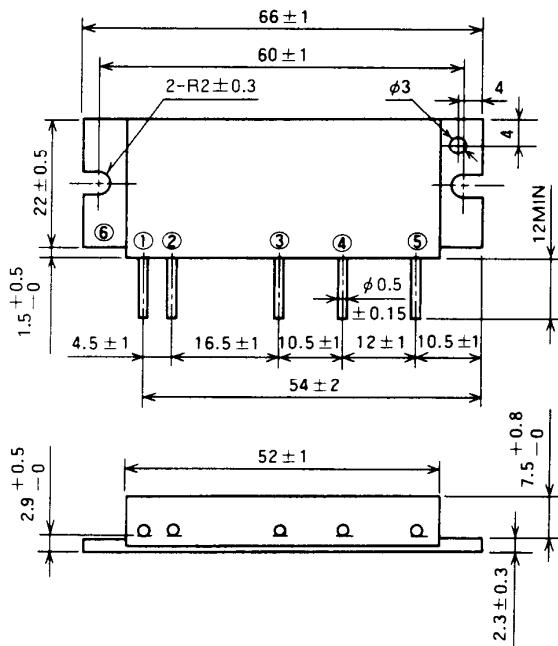
$$T_{j1} = 74.4^\circ\text{C}, T_{j2} = 80.3^\circ\text{C}, T_{j3} = 103.5^\circ\text{C}.$$

As the maximum junction temperature of these incorporated transistors T_{jmax} are 175°C , application under fully derated condition is ensured.

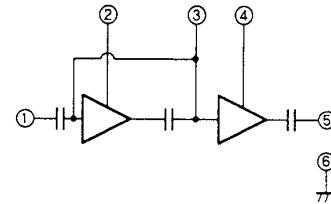
NOV. '97

OUTLINE DRAWING

Dimensions in mm



H3

BLOCK DIAGRAM

PIN :

- ① Pin : RF INPUT
- ② VCC1 : 1st. DC SUPPLY
- ③ VBB : BASE BIAS SUPPLY
- ④ VCC2 : 2nd. DC SUPPLY
- ⑤ PO : RF OUTPUT
- ⑥ GND : FIN

ABSOLUTE MAXIMUM RATINGS (Tc = 25°C unless otherwise noted)

Symbol	Parameter	Conditions	Ratings	Unit
Vcc	Supply voltage		17	V
Vbb	Base bias		10	V
Icc	Total current		10	A
Pin(max)	Input power	ZG = ZL = 50 Ω	0.5	W
Po(max)	Output power	ZG = ZL = 50 Ω	40	W
Tc(OP)	Operation case temperature		- 30 to 110	°C
Tstg	Storage temperature		- 40 to 110	°C

Note. Above parameters are guaranteed independently.

ELECTRICAL CHARACTERISTICS (Tc = 25°C unless otherwise noted)

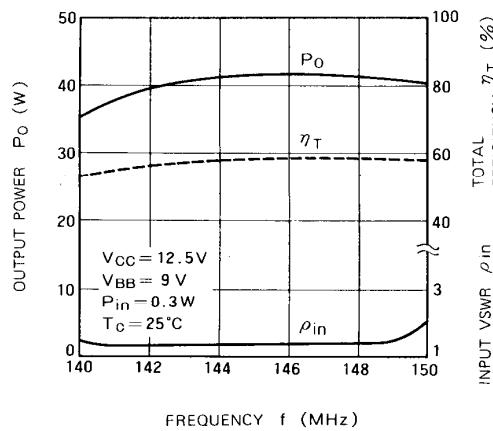
Symbol	Parameter	Test conditions	Limits		Unit
			Min	Max	
f	Frequency range		144	148	MHz
Po	Output power	Pin = 0.3W Vcc = 12.5V	37		W
ητ	Total efficiency	Vbb = 9V ZG = ZL = 50 Ω	50		%
2fo	2nd. harmonic			- 25	dBc
3fo	3rd. harmonic			- 30	dBc
Pin	Input VSWR			2.2	-
-	Load VSWR tolerance	Vcc = 15.2V, Vbb = 9V Po = 30W (Pin : controlled) Load VSWR ≥ 20:1 (All phase), 5sec. ZG = 50 Ω	No degradation or destroy		-

Note. Above parameters, ratings, limits and conditions are subject to change.

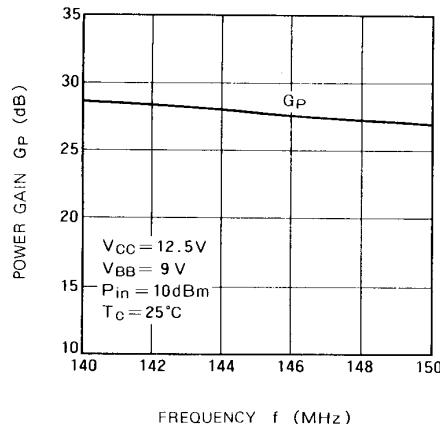
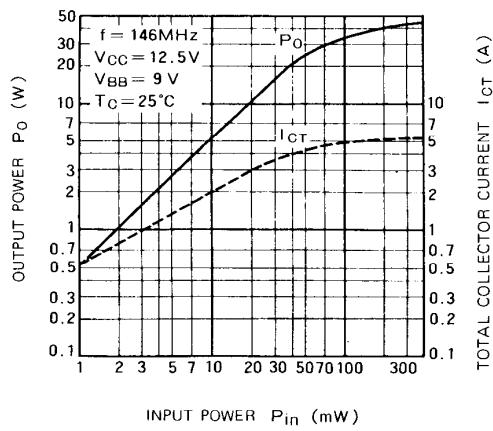
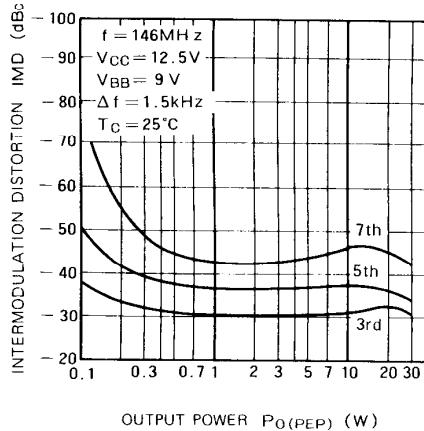
NOV. '97



TYPICAL PERFORMANCE DATA

OUTPUT POWER, TOTAL EFFICIENCY,
INPUT VSWR VS. FREQUENCY

POWER GAIN VS. FREQUENCY

OUTPUT POWER, TOTAL COLLECTOR
CURRENT VS. INPUT POWERINTERMODULATION DISTORTION
VS. OUTPUT POWER

DESIGN CONSIDERATION OF HEAT RADIATION.

Please refer to following consideration when designing heat sink.

1. Junction temperature of incorporated transistors at standard operation.

- (1) Thermal resistance between junction and package of incorporated transistors.

a) First stage transistor

$$R_{th(j-c)1} = 3^\circ\text{C/W (Typ.)}$$

b) Final stage transistor

$$R_{th(j-c)2} = 1.5^\circ\text{C/W (Typ.)}$$

- (2) Junction temperature of incorporated transistors at standard operation.

- Conditions for standard operation.

$P_o = 30\text{W}$, $V_{CC} = 12.5\text{V}$, $P_{in} = 0.1\text{W}$, $\eta_T = 50\%$ (minimum rating), P_{o1} (Note 1) = 2W , $I_T = 4.8\text{A}$ (I_{T1} ⁽²⁾ = 0.4A , I_{T2} ⁽³⁾ = 4.4A)

Note 1: Output power of the first stage transistor

Note 2: Circuit current of the first stage transistor

Note 3: Circuit current of the final stage transistor

- Junction temperature of the first stage transistor

$$\begin{aligned} T_{j1} &= (V_{CC} \times I_{T1} - P_{o1} + P_{in}) \times R_{th(j-c)2} + T_c \quad (4) \\ &= (12.5 \times 0.4 - 2 + 0.1) \times 3 + T_c \\ &= 9.3 + T_c \quad (\text{ }^\circ\text{C}) \end{aligned}$$

Note 4: Package temperature of device

- Junction temperature of the final stage transistor

$$\begin{aligned} T_{j2} &= (V_{CC} \times I_{T2} - P_o + P_{o1}) \times R_{th(j-c)2} + T_c \\ &= (12.5 \times 4.4 - 30 + 2) \times 1.5 + T_c \\ &= 40.5 + T_c \quad (\text{ }^\circ\text{C}) \end{aligned}$$

2. Heat sink design

In thermal design of heat sink, try to keep the package temperature at the upper limit of the operating ambient temperature (normally $T_a = 60^\circ\text{C}$) and at the output power of 30W below 90°C .

The thermal resistance $R_{th(c-a)}$ ⁽⁵⁾ of the heat sink to realize this:

$$\begin{aligned} R_{th(c-a)} &= \frac{T_c - T_a}{(P_o/\eta_T) - P_o + P_{in}} = \frac{90 - 60}{(30/0.5) - 30 + 0.1} \\ &= 1.00 \quad (\text{ }^\circ\text{C/W}) \end{aligned}$$

Note 5: Inclusive of the contact thermal resistance between device and heat sink

Mounting the heat sink of the above thermal resistance on the device,

$$T_{j1} = 110^\circ\text{C}, T_{j2} = 131^\circ\text{C} \text{ at } T_a = 60^\circ\text{C}, T_c = 90^\circ\text{C}.$$

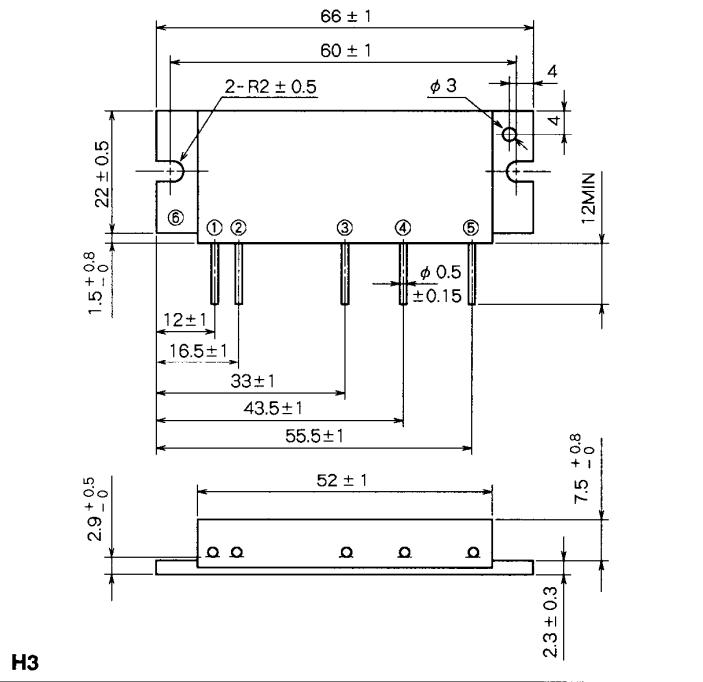
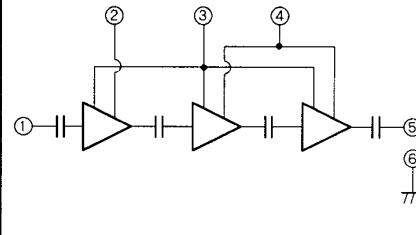
In the annual average of ambient temperature is 30°C ,

$$T_{j1} = 70^\circ\text{C}, T_{j2} = 101^\circ\text{C}$$

As the maximum junction temperature of these incorporated transistors T_{jmax} are 175°C , application under fully derated condition is ensured.

OUTLINE DRAWING

Dimensions in mm

**BLOCK DIAGRAM**

PIN :

- ①Pin : RF INPUT
- ②VCC1 : 1st. DC SUPPLY
- ③VBB : BASE BIAS SUPPLY
- ④VCC2 : 2nd. DC SUPPLY
- ⑤Po : RF OUTPUT
- ⑥GND : FIN

ABSOLUTE MAXIMUM RATINGS ($T_c = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Ratings	Unit
Vcc	Supply voltage		17	V
Vbb	Base bias		10	V
Icc	Total current		8	A
Pin(max)	Input power	$V_{CC1}=12.5V, V_{BB}=9V, Z_G=Z_L=50\Omega$	2	W
Po(max)	Output power	$Z_G = Z_L = 50 \Omega$	25	W
Tc(OP)	Operation case temperature		- 30 to 110	°C
Tstg	Storage temperature		- 40 to 110	°C

Note. Above parameters are guaranteed independently.

ELECTRICAL CHARACTERISTICS ($T_c = 25^\circ\text{C}$ unless otherwise noted)

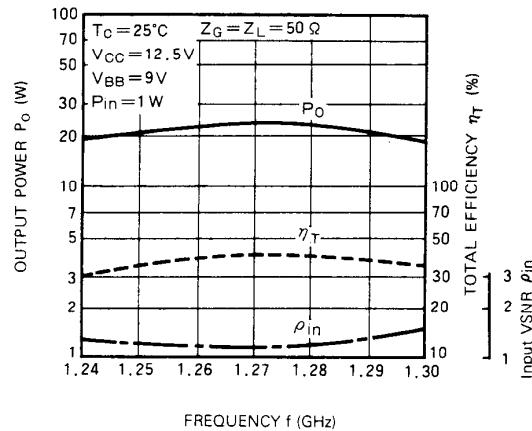
Symbol	Parameter	Test conditions	Limits		Unit
			Min	Max	
f	Frequency range		1240	1300	MHz
Po	Output power	$V_{CC1} = V_{CC2} = 12.5V$	18		W
η_T	Total efficiency	$V_{BB} = 9V$	28		%
2fo	2nd. harmonic	$P_{in} = 1W$		- 45	dBc
ρ_{in}	Input VSWR	$Z_G = Z_L = 50 \Omega$		2.0	-
Ibb	Base bias current			500	mA
Gp	Linear power gain	$V_{CC1} = V_{CC2} = 12.5V, V_{BB} = 9V, P_{in} = 10\text{dBm}, Z_G = Z_L = 50\Omega$	13		dB
IMD3	3rd. intermodulation distortion	$V_{CC1}=V_{CC2}=12.5V, V_{BB}=9V, \Delta f=10\text{kHz}$		- 24	dBc
IMD5	5th. intermodulation distortion	$P_{o(PEP)} \leq 14W, Z_G=Z_L=50\Omega$		- 31	dBc
-	Load VSWR tolerance	$V_{CC1} = V_{CC2} = 15.2V, V_{BB} = 9V, P_{in} = 18W(P_{in} : controlled), Z_G=50\Omega$ Load VSWR = 16 : 1(All phase).	No degradation or destroy		-

Note. Above parameters, ratings, limits and conditions are subject to change.

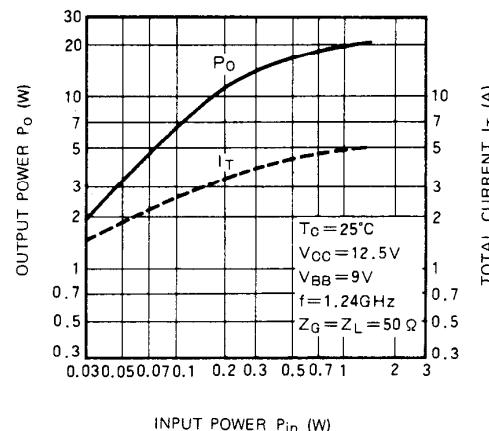
1240-1300MHz, 12.5V, 18W, SSB MOBILE RADIO

TYPICAL PERFORMANCE DATA

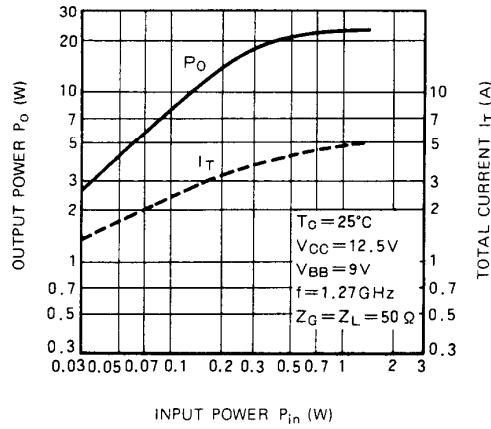
OUTPUT POWER, TOTAL EFFICIENCY, INPUT VSWR VS. FREQUENCY CHARACTERISTICS



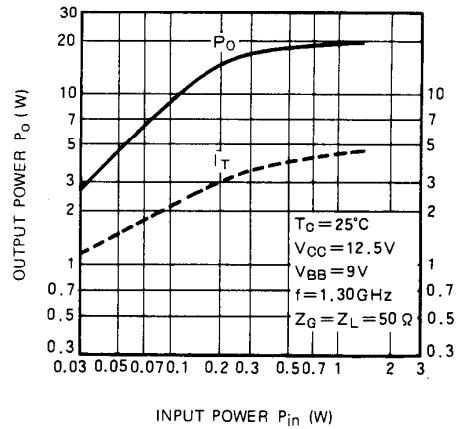
OUTPUT POWER, TOTAL CURRENT, VS. INPUT POWER CHARACTERISTICS



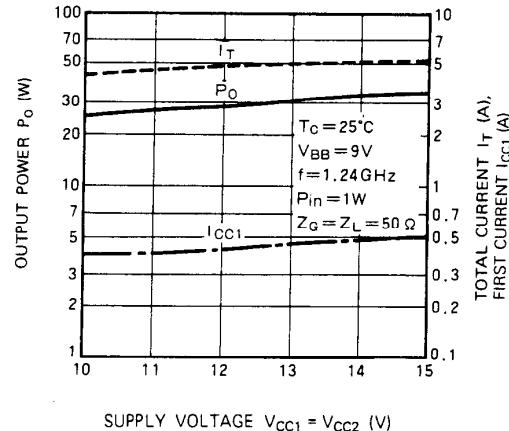
OUTPUT POWER, TOTAL CURRENT, VS. INPUT POWER CHARACTERISTICS



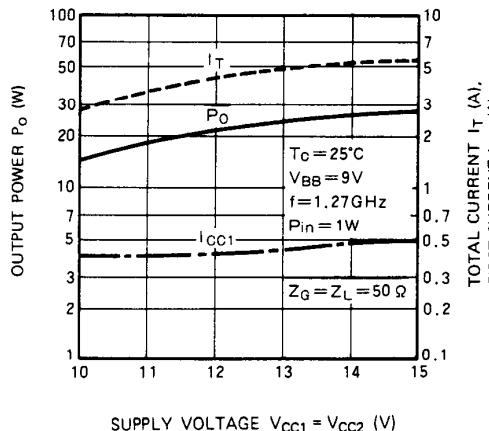
OUTPUT POWER, TOTAL CURRENT, VS. INPUT POWER CHARACTERISTICS



OUTPUT POWER, TOTAL CURRENT, FIRST CURRENT VS. SUPPLY VOLTAGE CHARACTERISTICS



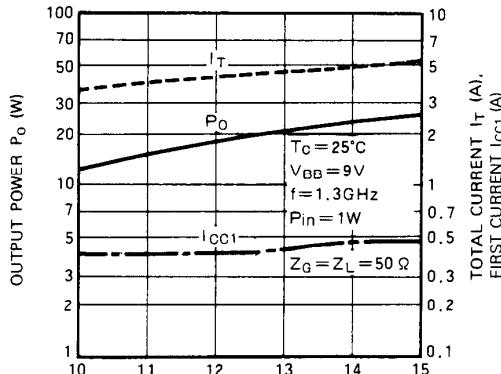
OUTPUT POWER, TOTAL CURRENT, FIRST CURRENT VS. SUPPLY VOLTAGE CHARACTERISTICS



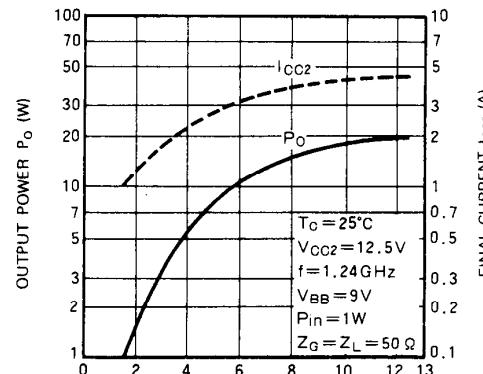
NOV. '97

1240-1300MHz, 12.5V, 18W, SSB MOBILE RADIO

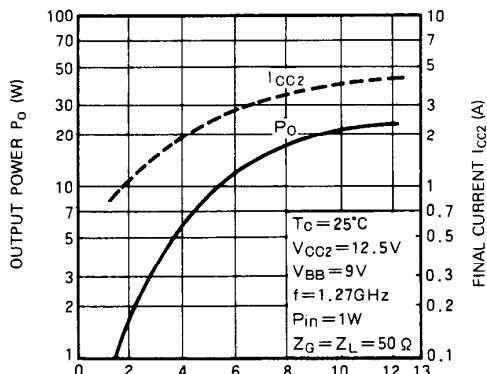
**OUTPUT POWER, TOTAL CURRENT,
FIRST CURRENT VS.
SUPPLY VOLTAGE CHARACTERISTICS**

SUPPLY VOLTAGE $V_{CC1} = V_{CC2}$ (V)

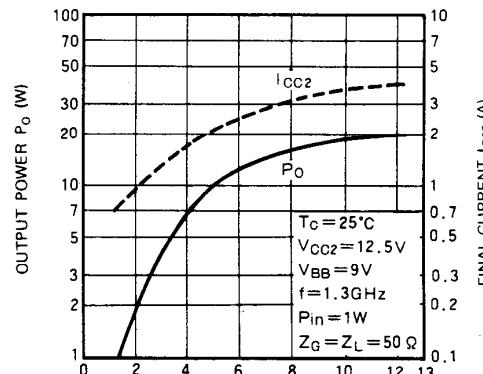
**OUTPUT POWER, FINAL
CURRENT VS. FIRST
VOLTAGE CHARACTERISTICS**

FIRST VOLTAGE V_{CC1} (V)

**OUTPUT POWER, FINAL
CURRENT VS. FIRST
VOLTAGE CHARACTERISTICS**

FIRST VOLTAGE V_{CC1} (V)

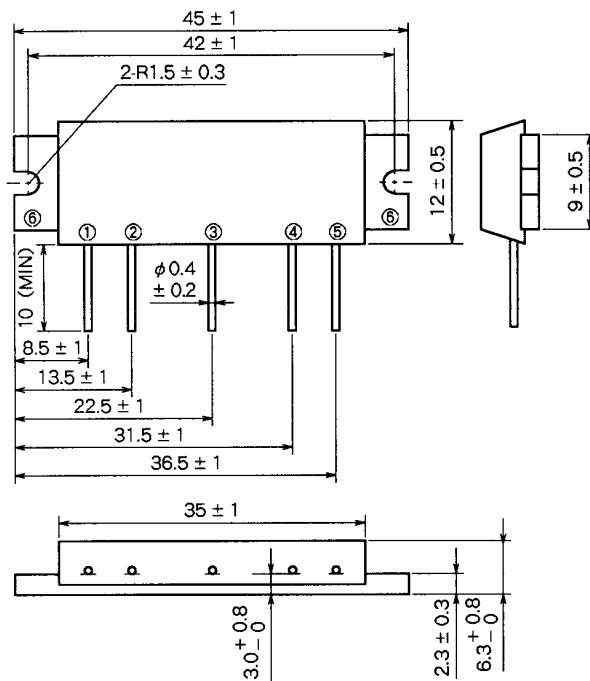
**OUTPUT POWER, FINAL
CURRENT VS. FIRST
CURRENT CHARACTERISTICS**

FIRST VOLTAGE V_{CC1} (V)

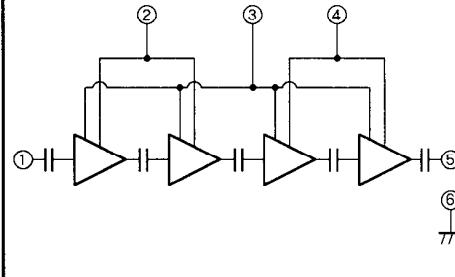
NOV. '97

OUTLINE DRAWING

Dimensions in mm



H13

BLOCK DIAGRAM

PIN :

- ①Pin : RF INPUT
- ②VCC1 : 1st. DC SUPPLY
- ③VBB : BASE BIAS SUPPLY
- ④VCC2 : 2nd. DC SUPPLY
- ⑤PO : RF OUTPUT
- ⑥GND : FIN

ABSOLUTE MAXIMUM RATINGS ($T_c = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Ratings	Unit
Vcc1	Supply voltage		9	V
Vcc2			16	V
Vbb	Base bias		9	V
Icc	Total current		1.5	A
Pin(max)	Input power	$Z_G = Z_L = 50 \Omega$	10	mW
Por(max)	Output power	$Z_G = Z_L = 50 \Omega$	4	W
Tc(OP)	Operation case temperature		- 20 to 100	°C
Tstg	Storage temperature		- 40 to 110	°C

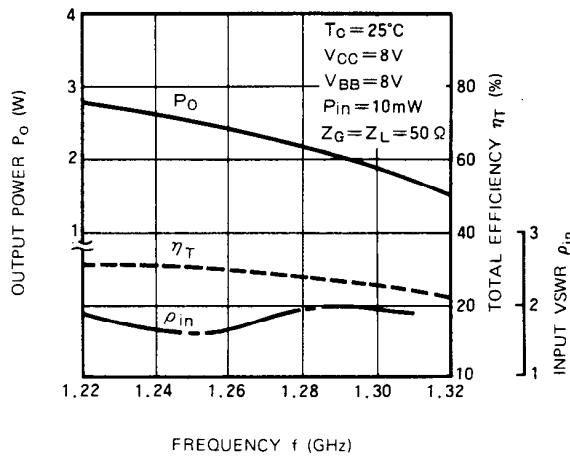
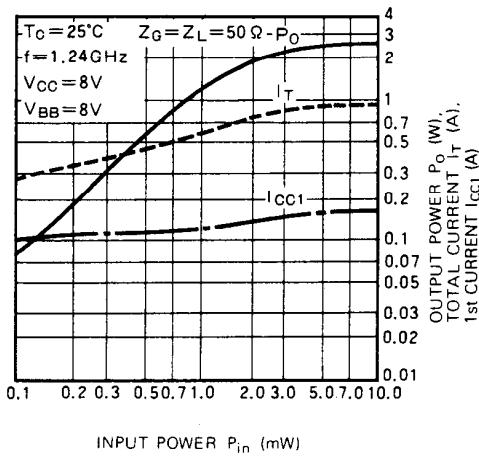
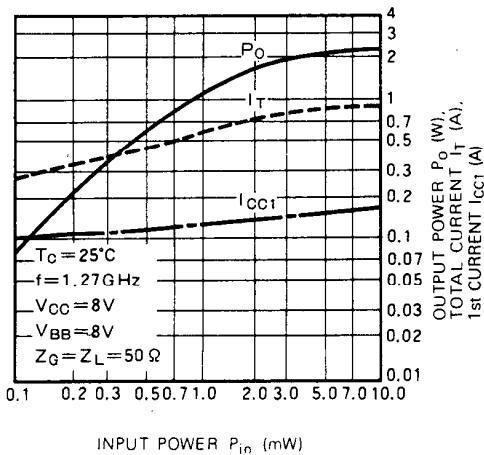
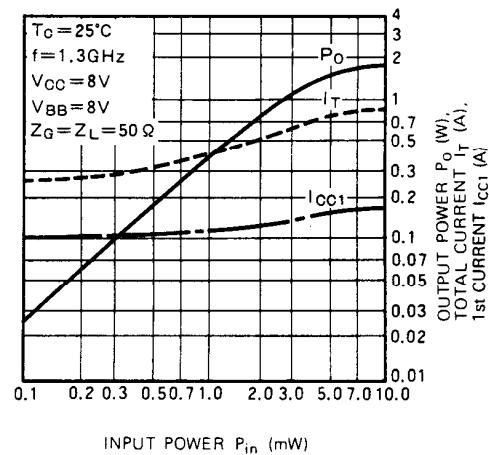
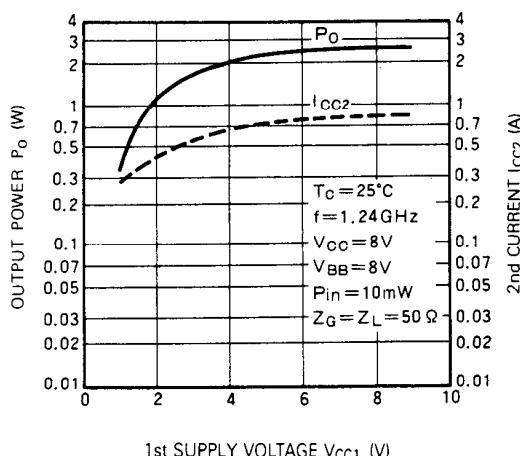
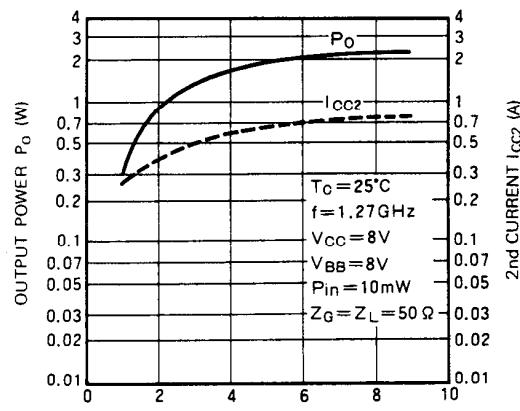
Note. Above parameters are guaranteed independently.

ELECTRICAL CHARACTERISTICS ($T_c = 25^\circ\text{C}$ unless otherwise noted)

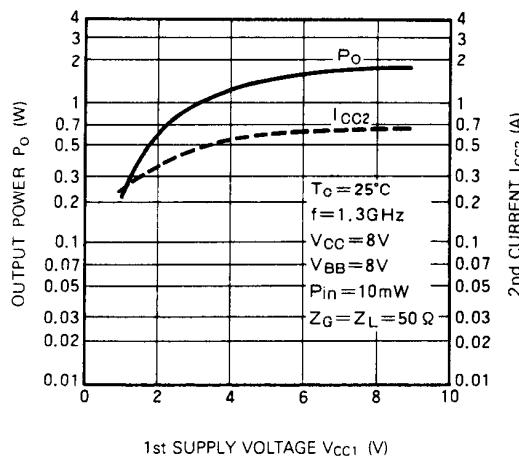
Symbol	Parameter	Test conditions	Limits		Unit
			Min	Max	
f	Frequency range		1240	1300	MHz
po	Output power		1.2		W
η T	Total efficiency	$V_{CC1} = V_{CC2} = V_{BB} = 8V$ $P_{in} = 10mW$ $Z_G = Z_L = 50\Omega$	18		%
2fo	2nd. harmonic			- 30	dBc
3fo	3rd. harmonic			- 35	dBc
ρ in	Input VSWR			2.5	-
-	Load VSWR tolerance	$V_{CC1} = 9V, V_{CC2} = 15.2V, V_{BB} = 9V$ $P_o = 1.5W (Pin : controlled), Z_G = 50\Omega$ Load VSWR=10:1 (All phase), 5sec	No degradation or destroy		-
IMD3	3rd. inter modulation distortion	$V_{CC1}=V_{CC2}=V_{BB}=8V$ $P_o(PEP)=1.26W, \Delta f=20kHz, Z_G=Z_L=50\Omega$		- 23	dBc
IMD5	5th. inter modulation distortion	$V_{CC1}=V_{CC2}=V_{BB}=8V$ $P_o(PEP)=1.26W, \Delta f=20kHz, Z_G=Z_L=50\Omega$		- 30	dBc

Note. Above parameters, ratings, limits and conditions are subject to change.

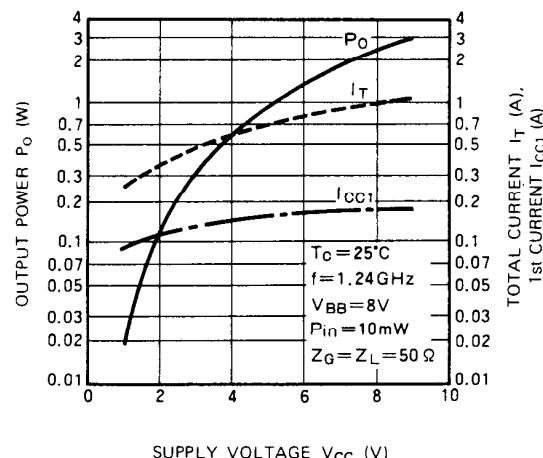
TYPICAL PERFORMANCE DATA

OUTPUT POWER, TOTAL EFFICIENCY,
 ρ_{in} VS. FREQUENCY CHARACTERISTICSOUTPUT POWER, TOTAL CURRENT,
1st CURRENT VS. INPUT
POWER CHARACTERISTICSOUTPUT POWER, TOTAL CURRENT,
1st CURRENT VS. INPUT
POWER CHARACTERISTICSOUTPUT POWER, TOTAL CURRENT,
1st CURRENT VS. INPUT
POWER CHARACTERISTICSOUTPUT POWER, 2nd CURRENT
VS. 1st SUPPLY VOLTAGE
CHARACTERISTICSOUTPUT POWER, 2nd CURRENT
VS. 1st SUPPLY VOLTAGE
CHARACTERISTICS

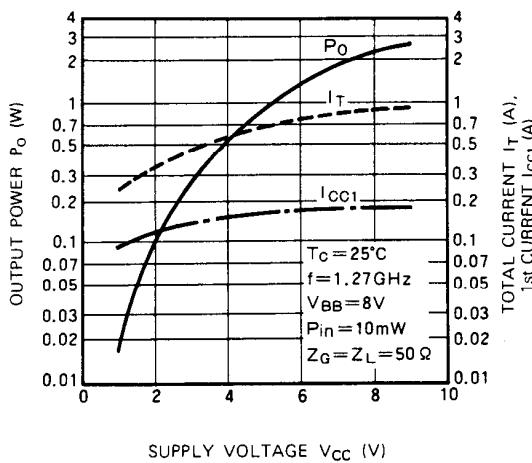
**OUTPUT POWER, 2nd CURRENT
VS. 1st SUPPLY VOLTAGE
CHARACTERISTICS**



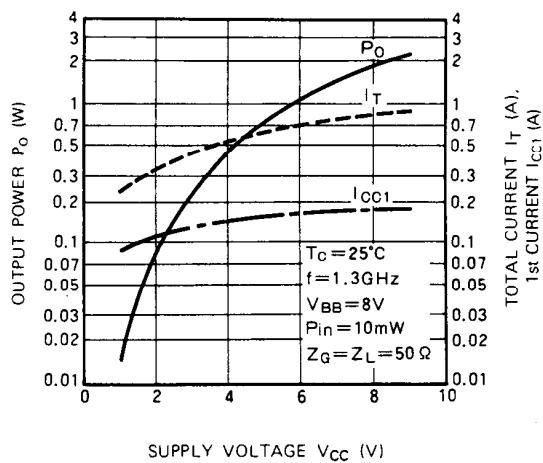
**OUTPUT POWER, TOTAL CURRENT,
1st CURRENT VS. SUPPLY
VOLTAGE CHARACTERISTICS**



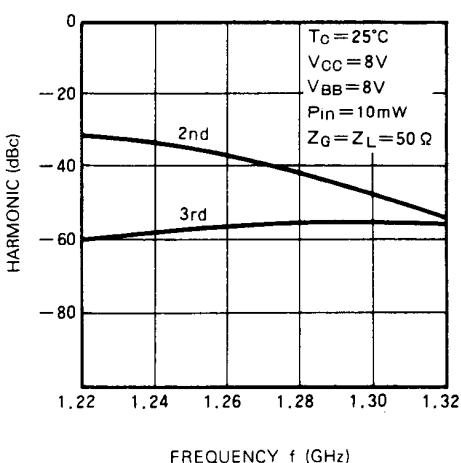
**OUTPUT POWER, TOTAL CURRENT,
1st CURRENT VS. SUPPLY
VOLTAGE CHARACTERISTICS**



**OUTPUT POWER, TOTAL CURRENT,
1st CURRENT VS. SUPPLY
VOLTAGE CHARACTERISTICS**



**2nd, 3rd HARMONIC VS. FREQUENCY
CHARACTERISTICS**



This datasheet has been download from:

www.datasheetcatalog.com

Datasheets for electronics components.